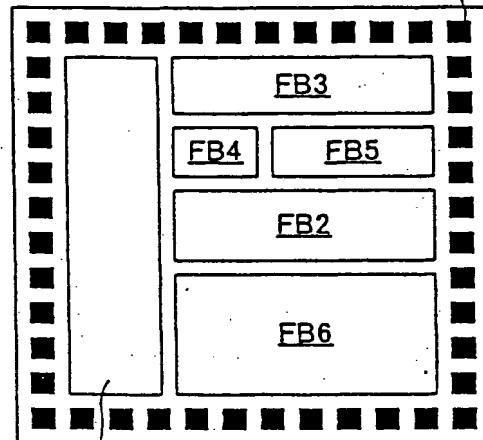


FIG. 1

100: SEMICONDUCTOR DEVICE

BP: BONDING PAD



FB1: FUNCTIONAL ELEMENT BLOCK

FIG. 2

100- SEMICONDUCTOR DEVICE

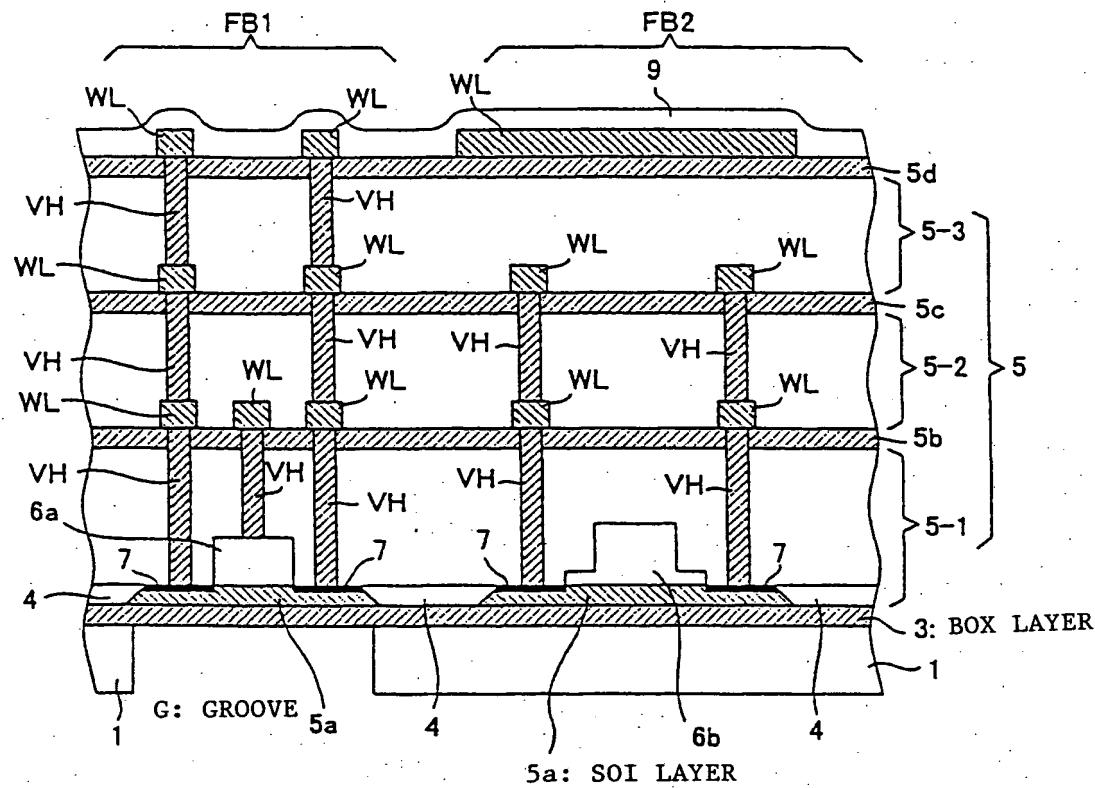


FIG. 3

100: SEMICONDUCTOR DEVICE

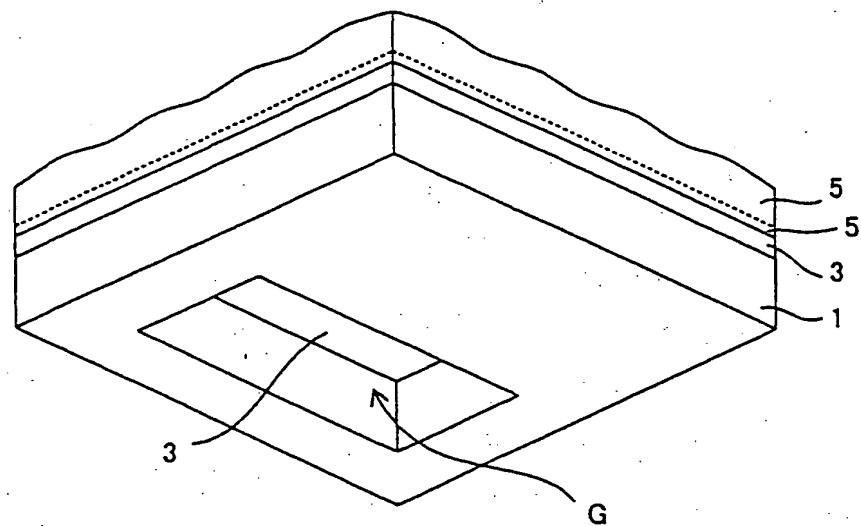


FIG. 4

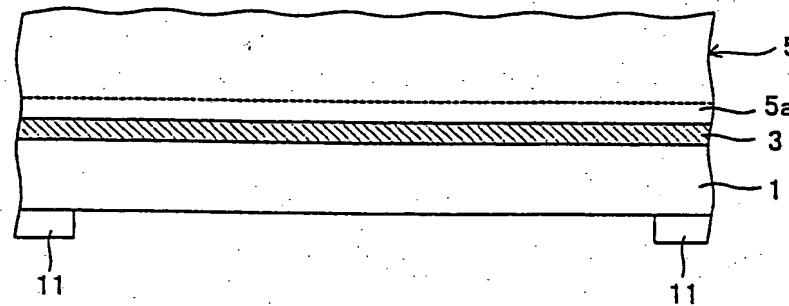


FIG. 5

100: SEMICONDUCTOR DEVICE

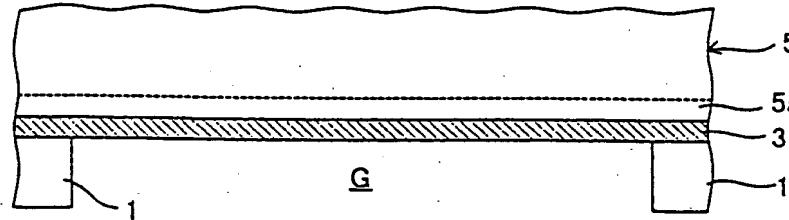
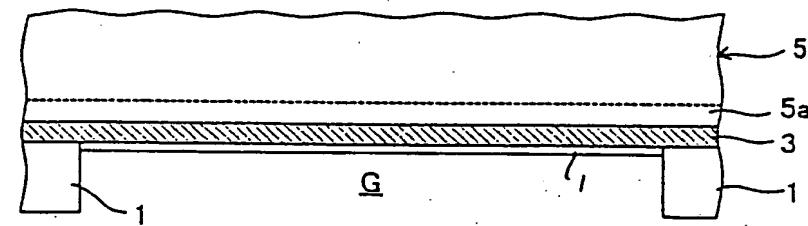


FIG. 5 A

FIG. 6



200: SEMICONDUCTOR DEVICE

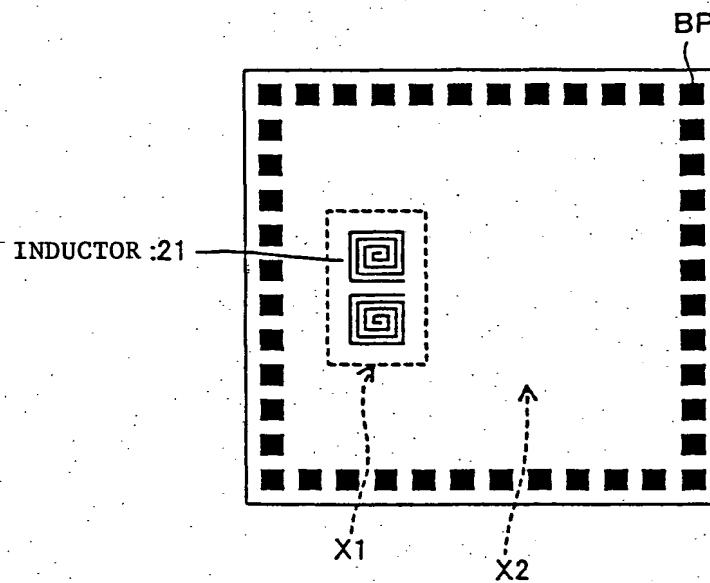


FIG. 7

200: SEMICONDUCTOR DEVICE

31: ETCHING MASK

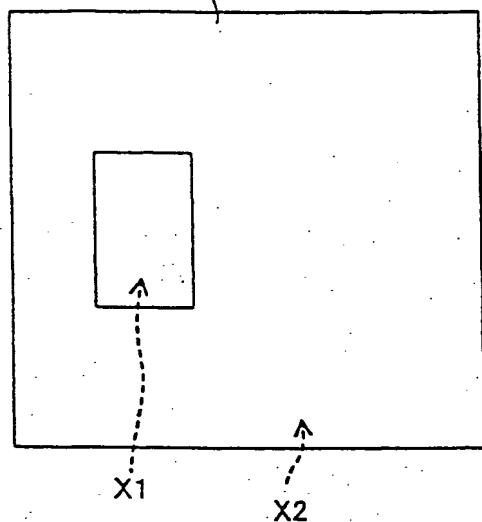


FIG. 8

300: SEMICONDUCTOR DEVICE

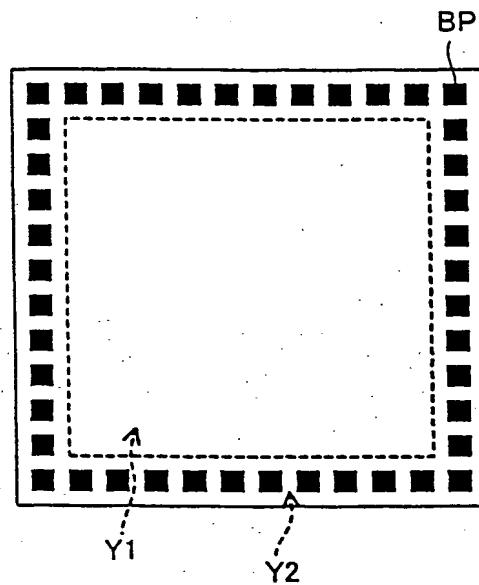


FIG. 9

300: SEMICONDUCTOR DEVICE

32-ETCHING MASK

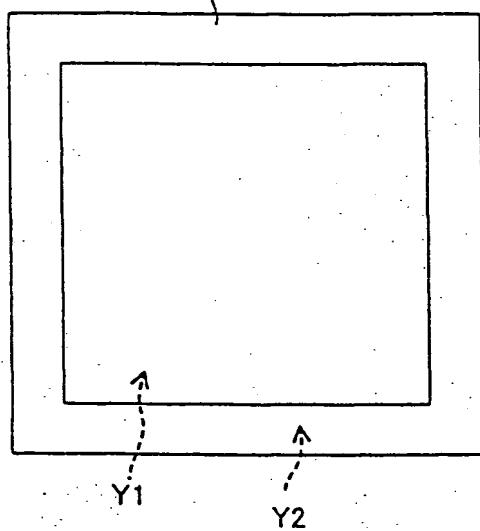


FIG. 10

100,200,300: SEMICONDUCTOR DEVICE

